AHTN Code	Product Description	Base Rate	Year 1	Year 2	Year 3	Year 4	Year 5	Year 6	Year 7	Year 8	Year 9	Year 10	Year 11	Year 12	Year 13	Year 14	Year 15	Year 16	Year 17	Year 18	Year 19	Year 20 and Subsequent Years
8486.20.59	--- Other	15 %	15 %	13.5 %	13.5 %	12 %	12 %	10.5 %	10.5 %	9 %	9 %	7.5 %	7.5 %	6 %	6 %	4.5 %	4.5 %	3 %	3 %	1.5 %	1.5 %	0 %
	- - Other:																					
8486.20.91	--- Lasercutters for cutting contacting tracks in semiconductor production by laser beam	15 %	15 %	13 %	13 %	13 %	11 %	11 %	9 %	9 %	7 %	7 %	5 %	5 %	3 %	3 %	0 %	0 %	0 %	0 %	0 %	0 %
8486.20.92	--- Machines for bending, folding and straightening semiconductor leads	15 %	15 %	13 %	13 %	11 %	11 %	9 %	9 %	7 %	7 %	5 %	5 %	3 %	0 %	0 %	0 %	0 %	0 %	0 %	0 %	0 %
8486.20.93	--- Resistance heated furnaces and ovens for the manufacture of semiconductor devices on semiconductor wafers	15 %	15 %	13 %	13 %	11 %	11 %	9 %	9 %	7 %	7 %	5 %	5 %	3 %	0 %	0 %	0 %	0 %	0 %	0 %	0 %	0 %
8486.20.94	--- Inductance or dielectric furnaces and ovens for the manufacture of semiconductor devices on semiconductor wafers	15 %	15 %	13 %	13 %	11 %	11 %	9 %	9 %	7 %	7 %	5 %	5 %	3 %	0 %	0 %	0 %	0 %	0 %	0 %	0 %	0 %
8486.20.95	--- Automated machines for the placement or the removal of components or contact elements on semiconductor materials	15 %	15 %	13 %	13 %	11 %	11 %	9 %	9 %	7 %	7 %	5 %	5 %	3 %	0 %	0 %	0 %	0 %	0 %	0 %	0 %	0 %
8486.20.99	--- Other	15 %	15 %	13 %	13 %	11 %	11 %	9 %	9 %	7 %	7 %	5 %	5 %	3 %	0 %	0 %	0 %	0 %	0 %	0 %	0 %	0 %
8486.30	**- Machines and apparatus for the manufacture of flat panel displays:**																					
8486.30.10	-- Apparatus for dry etching patterns on flat panel display substrates	15 %	15 %	13 %	13 %	11 %	11 %	9 %	9 %	7 %	7 %	5 %	5 %	3 %	0 %	0 %	0 %	0 %	0 %	0 %	0 %	0 %
8486.30.20	-- Apparatus for wet etching, developing, stripping or cleaning flat panel displays	15 %	15 %	13 %	13 %	11 %	11 %	9 %	9 %	7 %	7 %	5 %	5 %	3 %	0 %	0 %	0 %	0 %	0 %	0 %	0 %	0 %
8486.30.30	-- Chemical vapour deposition apparatus for flat panel display production; spinners for coating photosensitive emulsions on flat panel display substrates; apparatus for physical deposition on flat panel display substrates	15 %	15 %	13 %	13 %	11 %	11 %	9 %	9 %	7 %	7 %	5 %	5 %	3 %	0 %	0 %	0 %	0 %	0 %	0 %	0 %	0 %
8486.30.90	-- Other	15 %	15 %	13 %	13 %	13 %	11 %	11 %	9 %	9 %	7 %	7 %	5 %	5 %	3 %	3 %	0 %	0 %	0 %	0 %	0 %	0 %
8486.40	**- Machines and apparatus specified in Note 9 (C) to this Chapter:**																					
8486.40.10	-- Focused ion beam milling machines to produce or repair masks and reticles for patterns on semiconductor devices	15 %	15 %	13 %	13 %	11 %	11 %	9 %	9 %	7 %	7 %	5 %	5 %	3 %	0 %	0 %	0 %	0 %	0 %	0 %	0 %	0 %
8486.40.20	-- Die attach apparatus, tape automated bonders, wire bonders and encapsulation equipment for the assembly of semiconductors; automated machines for transport, handling and storage of semiconductor wafers, wafer cassettes, wafer boxes and other materials for semiconductor devices	15 %	15 %	13 %	13 %	13 %	11 %	11 %	9 %	9 %	7 %	7 %	5 %	5 %	3 %	3 %	0 %	0 %	0 %	0 %	0 %	0 %
8486.40.30	-- Moulds for manufacture of semiconductor devices	15 %	15 %	13 %	13 %	11 %	11 %	9 %	9 %	7 %	7 %	5 %	5 %	3 %	0 %	0 %	0 %	0 %	0 %	0 %	0 %	0 %
8486.40.40	-- Optical stereoscopic microscopes fitted with equipment specifically designed for the handling and transport of semiconductor wafers or reticles	15 %	15 %	13 %	13 %	11 %	11 %	9 %	9 %	7 %	7 %	5 %	5 %	3 %	0 %	0 %	0 %	0 %	0 %	0 %	0 %	0 %
8486.40.50	-- Photomicrographic microscopes fitted with equipment specifically designed for the handling and transport of semiconductor wafers or reticles	15 %	15 %	13.5 %	13.5 %	12 %	12 %	10.5 %	10.5 %	9 %	9 %	7.5 %	7.5 %	6 %	6 %	4.5 %	4.5 %	3 %	3 %	1.5 %	1.5 %	0 %
8486.40.60	- - Electron beam microscopes fitted with equipment specifically designed for the handling and transport of semiconductor wafers or reticles	15 %	15 %	13 %	13 %	11 %	11 %	9 %	9 %	7 %	7 %	5 %	5 %	3 %	0 %	0 %	0 %	0 %	0 %	0 %	0 %	0 %
8486.40.70	-- Pattern generating apparatus of a kind used for producing masks or reticles from photoresist coated substrates	15 %	15 %	13 %	13 %	11 %	11 %	9 %	9 %	7 %	7 %	5 %	5 %	3 %	0 %	0 %	0 %	0 %	0 %	0 %	0 %	0 %
8486.40.90	-- Other	15 %	15 %	13.5 %	13.5 %	12 %	12 %	10.5 %	10.5 %	9 %	9 %	7.5 %	7.5 %	6 %	6 %	4.5 %	4.5 %	3 %	3 %	1.5 %	1.5 %	0 %
8486.90	**- Parts and accessories:**																					
	- - Of machines and apparatus for the manufacture of boules or wafers:																					
8486.90.11	--- Of apparatus for rapid heating of semiconductor wafers	15 %	15 %	13 %	13 %	11 %	11 %	9 %	9 %	7 %	7 %	5 %	5 %	3 %	0 %	0 %	0 %	0 %	0 %	0 %	0 %	0 %
8486.90.12	--- Of spin dryers for semiconductor wafer processing	15 %	15 %	13 %	13 %	11 %	11 %	9 %	9 %	7 %	7 %	5 %	5 %	3 %	0 %	0 %	0 %	0 %	0 %	0 %	0 %	0 %
8486.90.13	--- Of machines for working any material by removal of material, by laser or other light or photon beam in the production of semiconductor wafers	15 %	15 %	13 %	13 %	11 %	11 %	9 %	9 %	7 %	7 %	5 %	5 %	3 %	0 %	0 %	0 %	0 %	0 %	0 %	0 %	0 %
	- - - Of machines for sawing monocrystal semiconductor boules into slices, or wafers into chips:																					
8486.90.14	---- Tool holders and self-opening dieheads; work holders; dividing heads and other special attachments for machine tools	15 %	15 %	13 %	13 %	13 %	11 %	11 %	9 %	9 %	7 %	7 %	5 %	5 %	3 %	3 %	0 %	0 %	0 %	0 %	0 %	0 %
8486.90.15	---- Other	15 %	15 %	13 %	13 %	11 %	11 %	9 %	9 %	7 %	7 %	5 %	5 %	3 %	0 %	0 %	0 %	0 %	0 %	0 %	0 %	0 %
8486.90.16	--- Of grinding, polishing and lapping machines for processing of semiconductor wafers	15 %	15 %	13 %	13 %	11 %	11 %	9 %	9 %	7 %	7 %	5 %	5 %	3 %	0 %	0 %	0 %	0 %	0 %	0 %	0 %	0 %
8486.90.17	--- Of apparatus for growing or pulling monocrystal semiconductor boules	15 %	15 %	13 %	13 %	11 %	11 %	9 %	9 %	7 %	7 %	5 %	5 %	3 %	0 %	0 %	0 %	0 %	0 %	0 %	0 %	0 %
8486.90.19	--- Other	15 %	15 %	13 %	13 %	11 %	11 %	9 %	9 %	7 %	7 %	5 %	5 %	3 %	0 %	0 %	0 %	0 %	0 %	0 %	0 %	0 %
	- - Of machines and apparatus for the manufacture of semiconductor devices or of electronic integrated circuits:																					
8486.90.21	--- Of chemical vapour deposition apparatus for semiconductor production	15 %	15 %	13 %	13 %	11 %	11 %	9 %	9 %	7 %	7 %	5 %	5 %	3 %	0 %	0 %	0 %	0 %	0 %	0 %	0 %	0 %
8486.90.22	--- Of epitaxial deposition machines for semiconductor wafers; of spinners for coating photographic emulsions on semiconductor wafers	15 %	15 %	13 %	13 %	11 %	11 %	9 %	9 %	7 %	7 %	5 %	5 %	3 %	0 %	0 %	0 %	0 %	0 %	0 %	0 %	0 %

AHTN Code	Product Description	Base Rate	Year 1	Year 2	Year 3	Year 4	Year 5	Year 6	Year 7	Year 8	Year 9	Year 10	Year 11	Year 12	Year 13	Year 14	Year 15	Year 16	Year 17	Year 18	Year 19	Year 20 and Subsequent Years
8486.90.23	--- Of ion implanters for doping semiconductor materials; of apparatus for physical deposition by sputtering on semiconductor wafers; of physical deposition apparatus for semiconductor production; of direct write-on-wafer apparatus, step and repeat aligners and other lithography equipment	15 %	15 %	13 %	13 %	11 %	11 %	9 %	9 %	7 %	7 %	5 %	5 %	3 %	0 %	0 %	0 %	0 %	0 %	0 %	0 %	0 %
	- - - Of spraying appliances for etching, stripping or cleaning semiconductor wafers; of apparatus for wet etching, developing, stripping or cleaning semiconductor wafers; of dry-etching patterns on semiconductor materials:																					
8486.90.24	---- Tool holders and self-opening dieheads; work holders; dividing heads and other special attachments for machine tools	15 %	15 %	13 %	13 %	11 %	11 %	9 %	9 %	7 %	7 %	5 %	5 %	3 %	0 %	0 %	0 %	0 %	0 %	0 %	0 %	0 %
8486.90.25	---- Other	15 %	15 %	13 %	13 %	11 %	11 %	9 %	9 %	7 %	7 %	5 %	5 %	3 %	0 %	0 %	0 %	0 %	0 %	0 %	0 %	0 %
	- - - Of dicing machines for scribing or scoring semiconductor wafers; of lasercutters for cutting tracks in semiconductor production by laser beam; of machines for bending, folding and straightening semiconductor leads:																					
8486.90.26	---- Tool holders and self-opening dieheads; workholders; dividing heads and other special attachments for machine tools	15 %	15 %	13 %	13 %	11 %	11 %	9 %	9 %	7 %	7 %	5 %	5 %	3 %	0 %	0 %	0 %	0 %	0 %	0 %	0 %	0 %
8486.90.27	---- Other	15 %	15 %	13 %	13 %	11 %	11 %	9 %	9 %	7 %	7 %	5 %	5 %	3 %	0 %	0 %	0 %	0 %	0 %	0 %	0 %	0 %
8486.90.28	--- Of resistance heated furnaces and ovens for the manufacture of semiconductor devices on semiconductor wafers; of inductance or dielectric furnaces and ovens for the manufacture of semiconductor devices on semiconductor wafers	15 %	15 %	13 %	13 %	11 %	11 %	9 %	9 %	7 %	7 %	5 %	5 %	3 %	0 %	0 %	0 %	0 %	0 %	0 %	0 %	0 %
8486.90.29	--- Other	15 %	15 %	13 %	13 %	11 %	11 %	9 %	9 %	7 %	7 %	5 %	5 %	3 %	0 %	0 %	0 %	0 %	0 %	0 %	0 %	0 %
	- - Of machines and apparatus for the manufacture of flat panel displays:																					
8486.90.31	--- Of apparatus for dry etching patterns on flat panel display substrates	15 %	15 %	13 %	13 %	11 %	11 %	9 %	9 %	7 %	7 %	5 %	5 %	3 %	0 %	0 %	0 %	0 %	0 %	0 %	0 %	0 %
	- - - Of apparatus for wet etching, developing, stripping or cleaning flat panel displays:																					
8486.90.32	---- Tool holders and self-opening dieheads; work holders; dividing heads and other special attachments for machine tools	15 %	15 %	13 %	13 %	11 %	11 %	9 %	9 %	7 %	7 %	5 %	5 %	3 %	0 %	0 %	0 %	0 %	0 %	0 %	0 %	0 %
8486.90.33	---- Other	15 %	15 %	13 %	13 %	11 %	11 %	9 %	9 %	7 %	7 %	5 %	5 %	3 %	0 %	0 %	0 %	0 %	0 %	0 %	0 %	0 %
8486.90.34	--- Of chemical vapour deposition apparatus for flat panel display production	15 %	15 %	13 %	13 %	11 %	11 %	9 %	9 %	7 %	7 %	5 %	5 %	3 %	0 %	0 %	0 %	0 %	0 %	0 %	0 %	0 %
8486.90.35	--- Of spinners for coating photosensitive emulsions on flat panel display substrates	15 %	15 %	13 %	13 %	11 %	11 %	9 %	9 %	7 %	7 %	5 %	5 %	3 %	0 %	0 %	0 %	0 %	0 %	0 %	0 %	0 %
	emulsions on flat panel display substrates																					
8486.90.36	--- Of apparatus for physical deposition on flat panel display substrates	15 %	15 %	13 %	13 %	11 %	11 %	9 %	9 %	7 %	7 %	5 %	5 %	3 %	0 %	0 %	0 %	0 %	0 %	0 %	0 %	0 %
8486.90.39	--- Other	15 %	15 %	13 %	13 %	11 %	11 %	9 %	9 %	7 %	7 %	5 %	5 %	3 %	0 %	0 %	0 %	0 %	0 %	0 %	0 %	0 %
	- - Of machines or apparatus specified in Note 9 (C) to this Chapter:																					
8486.90.41	--- Of focused ion beam milling machine to produce or repair masks and reticles for patterns on semiconductor devices	15 %	15 %	13 %	13 %	11 %	11 %	9 %	9 %	7 %	7 %	5 %	5 %	3 %	0 %	0 %	0 %	0 %	0 %	0 %	0 %	0 %
8486.90.42	--- Of die attach apparatus, tape automated bonders, wire bonders and of encapsulation equipment for assembly of semiconductors	15 %	15 %	13 %	13 %	11 %	11 %	9 %	9 %	7 %	7 %	5 %	5 %	3 %	0 %	0 %	0 %	0 %	0 %	0 %	0 %	0 %
8486.90.43	--- Of automated machines for the transport, handling and storage of semiconductor wafers, wafer cassettes, wafer boxes and other materials for semiconductor devices	15 %	15 %	13 %	13 %	11 %	11 %	9 %	9 %	7 %	7 %	5 %	5 %	3 %	0 %	0 %	0 %	0 %	0 %	0 %	0 %	0 %
8486.90.44	--- Of optical stereoscopic and photomicrographic microscopes fitted with equipment specifically designed for the handling and transport of semiconductor wafers or reticles	15 %	15 %	13 %	13 %	11 %	11 %	9 %	9 %	7 %	7 %	5 %	5 %	3 %	0 %	0 %	0 %	0 %	0 %	0 %	0 %	0 %
8486.90.45	--- Of electron beam microscopes fitted with equipment specifically designed for the handling and transport of semiconductor wafers or reticles	15 %	15 %	13 %	13 %	11 %	11 %	9 %	9 %	7 %	7 %	5 %	5 %	3 %	0 %	0 %	0 %	0 %	0 %	0 %	0 %	0 %
8486.90.46	--- Of pattern generating apparatus of a kind used for producing masks or reticles from photoresist coated substrates, including printed circuit assemblies	15 %	15 %	13 %	13 %	11 %	11 %	9 %	9 %	7 %	7 %	5 %	5 %	3 %	0 %	0 %	0 %	0 %	0 %	0 %	0 %	0 %
8486.90.49	--- Other	15 %	15 %	13 %	13 %	11 %	11 %	9 %	9 %	7 %	7 %	5 %	5 %	3 %	0 %	0 %	0 %	0 %	0 %	0 %	0 %	0 %
84.87	**Machinery parts, not containing electrical connectors, insulators, coils, contacts or other electrical features, not specified or included elsewhere in this Chapter.**																					
8487.10.00	- Ships' or boats' propellers and blades therefor	15 %	15 %	13 %	13 %	11 %	11 %	9 %	9 %	7 %	7 %	5 %	5 %	3 %	0 %	0 %	0 %	0 %	0 %	0 %	0 %	0 %
8487.90.00	- Other	15 %	15 %	13.5 %	13.5 %	12 %	12 %	10.5 %	10.5 %	9 %	9 %	7.5 %	7.5 %	6 %	6 %	4.5 %	4.5 %	3 %	3 %	1.5 %	1.5 %	0 %